June-2010 Model of ILC (ILD) TPC

A Proposal

- 1. For our own conceptual "engineering" design of LC (ILD) TPC
- 2. Inputs to ILD physics simulation: space and material
- 3. Feedback to ILD detector integration: <u>cables & pipes</u>

LC TPC WP meeting WP5 Discussion 8 April 2010

Takeshi MATSUDA DESY/FLC & KEK/IPNS

June-2010 Model of LC (ILD) TPC



(II) Pixel readout TPC using TimePix:
(3) Multilayer GEM + Timepix
(4) Ingrid-MicroMEGAS + Timepix

<u>Make one "common model" for each of (I) and (II), at least for (I) in time,</u> though for (3) and (4) quite different ?

June-2010 Model of ILC (ILD) TPC Hardware

1. A model of **Endplate based on the Advanced Endplate**:

<u>Mechanics</u>: The current design with Dan's proposal (A) <u>Detector module</u>: Pad readout by S-ALTRO with the common pad size of 1mm x 4mm with a wire gate both for GEM and Micromegas/resistive-anode assuming a module structure ala Saclay (DESY) module

<u>Cooling</u>: The model by Bart but with $\Delta T = 0.1C$

2. A model of Field cage (FC) ala LP : with a central cathode, gas circulation, FC HV cable and cooling of FC resistors (if necessary) with TPC support

3. A model of <u>Electronics</u>:

S-ALTRO: a scheme of <u>low voltage supply</u> <u>Module HV</u>: DC converters or HV cables? DAQ: No extra DAQ component except those on the endplate? Any intermediate connection of cables?

4. Interface to Si trackers:

June-2010 Model of ILC (ILD) TPC Performance-Pad readout

5. A model of TPC operation:

Gas: T2K gas/Circulation Pressure: 2mb (goal) – 6mb (max)-10mb (safety) Contamination: O2/H2O Drift filed: up to 230V/cm Temperature (gas volume): 20.0C +- 0.1C

6. A model of TPC <u>performance</u>:

Z-dependent r- ϕ/z resolution: Extrapolations based on LP results (Neff, $\sigma(0)$, and with no-hodoscopes effect (ala Micromegas) Z-dependent r- ϕ/z double track separation (*1) : Based on the Z-dependent pad response for 1mm wide pads.

Dead area:

Based on the endplate/module model. Take the example of the Saclay/DESY module(*2)

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Advanced Endplate: S-ALTRO

S-ALTRO Team LC TPC collbaoration

High density, low power, low material electronics for TPC



ALICE TPC Electronics • PC board ~150µm Cu (0.1 X₀) • 22mW / cm² → 220W / m² • 0.3mm copper plate (0.2 X₀)



ALICE TPC



The S-ALTRO team at CERN

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ILC (ILD) TPC

Concept of Advanced Endplate with S-ALTRO LC (ILD) TPC with Pad Readout





MODULE DETAILS



Antoine JUNIQUE

With 2-phase CO2 cooling

LAYER STACKUP



18 layer PAD PCB

Concept of Endplate Cooling 2PHCO2 Cooling



Bart Verlaat/Nikhef